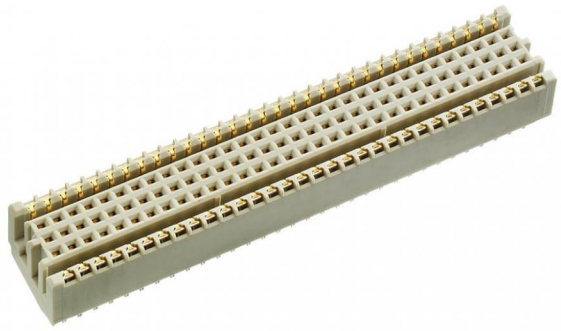
Product Data Sheet

DIN 41612 VME 64x female,
Part No. 306-60067-12



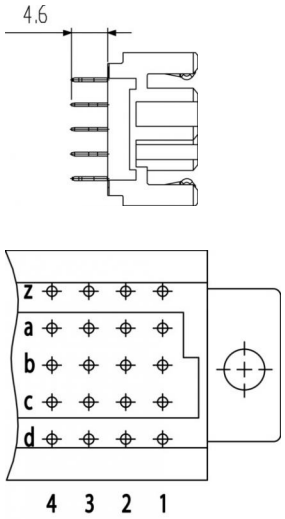


Illustration similar

Perpendicular

Press-fit

Rugged

- Termination length 4.6 mm
- 160 contacts
- Press-fit
- performance level 1
- DIN flange

» to product on www.ept.de

» to product group DIN 41612

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Product Data Sheet

DIN 41612 VME 64x female, Part No. 306-60067-12

Technical Specifications

Basics

Specification	IEC 61076-4-113
Performance Level	1
No. of Contacts	160
Termination Technology	Press-fit
Termination Length	4.6 mm
Operating Temperature Range	-55°C to +125°C

Material

Insulator Material	PBT glass filled UL 94 V-0
Contact Material	Copper alloy

Mechanical

Pitch	2.54 mm
Mating Force	160 N
Separating Force per Pin	> 0.15 N
Durability	500 mating cycles

Electrical

Operational Current	1.5 A
Contact Resistance	<20 mΩ
Clearance and Creepage	abc ≥ 1.2 mm, zd ≥ 1.0 mm
Insulation Resistance	10^4 MΩ
Test Voltage	1000 V

Approval / Compliance

UL file	E130314
Environment	RoHS compliant

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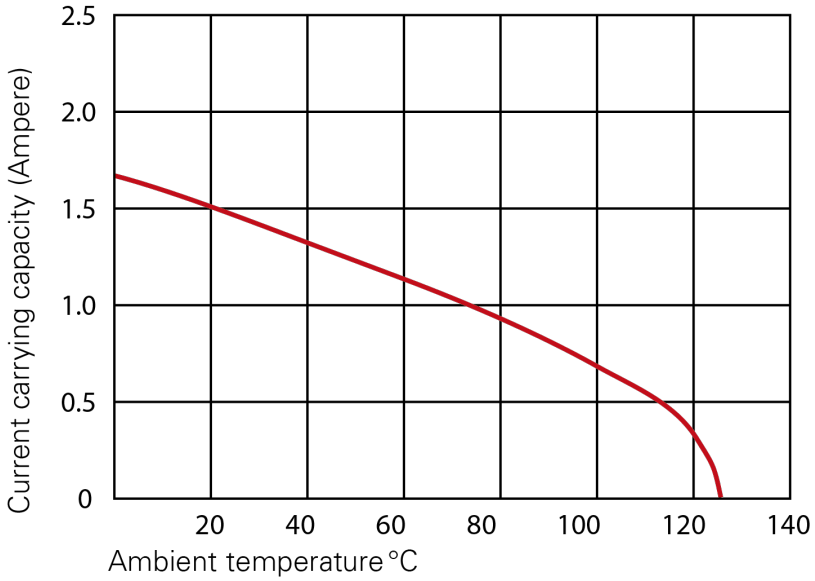
Derating Diagram



Type B, Q, C, R

20 °C	1.5 A
70 °C	1.1 A
100 °C	0.7 A

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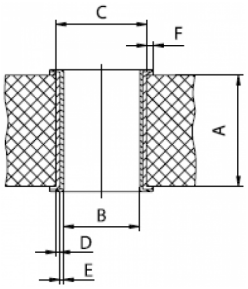
Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	imm. Sn plating, max. 1.5 µm
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

Material	pure Cu printed circuit boards
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	OSP*, z.B. GLICOAT-SMD (F2) with 0.12 - 0.15 µm
F Annular Ring	min. 0.1 mm

Material	HAL Sn printed circuit boards
Nominal Hole	**Ø 1.0 mm**
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 1.0 +0.09 / -0.06 mm
C Drill Hole	1.15 ±0.025 mm
D Cu Plating	min. 25 µm
E Surface	HAL Sn, 5 - 15 µm
F Annular Ring	min. 0.1 mm

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Drawings

Component data in 2D and 3D format you can download here:

» PDF » 3D IGES » 3D STEP » 3D PDF

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